









Applicable standard					
Rating	Operating temperature range	-35°C to +85°C(Note1)	Storage temperature range	-10°C to +60°C(Note3)	
	Operating humidity range 	20 % to 80 % (Note2)	Storage humidity range	40 % to 70 %(Note3)	
	Voltage	150 V AC/DC	Current 	AWG 26 : 2.5A AWG 28 : 2.0A AWG 30 : 1.0A AWG 32 : 1.0A	
	Applicable connector	DF13-2S-1.25C(##)	Applicable crimp contact 	DF13-2630SCFA(04) DF13G-2630SCFA DF13-3032SCFA	
<b>Specifications</b>					
Item	Test method		Requirements		QT AT
<b>Construction</b>					
General examination	Visually and by measuring instrument.		According to drawing.		X X
Marking	Confirmed visually.				X X
<b>Electric characteristics</b>					
Contact resistance	100 mA (DC or 1000Hz).		30 mΩ MAX.		X -
Insulation resistance	100 V DC.		500 MΩ MIN.		X -
Voltage proof	500 V AC for 1 min.		No flashover or breakdown.		X -
<b>Mechanical characteristics</b>					
Mechanical operation	50 times insertions and extractions.		① Contact resistance: 30 mΩ MAX. ② No damage, crack or looseness of parts.		X -
Vibration	Frequency 10 to 55 Hz, single amplitude 0.75 mm, at 2 h, for 3 directions.		① No electrical discontinuity of 1μs. ② No damage, crack or looseness of parts.		X -
Shock	490 m/s <sup>2</sup> duration of pulse 11 ms at 3 times for 3 directions.				X -
<b>Environmental characteristics</b>					
Rapid change of temperature	Temperature -55→ 5 to 35→+85→ 5 to 35 °C Time 30→ 5 to 15→ 30→ 5 to 15 min. Under 5 cycles.		① Contact resistance: 30mΩ MAX. ② Insulation resistance: 500 MΩ MIN. ③ No damage, crack or looseness of parts.		X -
Damp heat (Steady state)	Exposed at 40 ± 2 °C, 90 to 95 %, 96 h.				X -
Resistance to soldering heat 	1) Flow soldering 250°C, for 10 sec. 2) Manual soldering Soldering iron temperature :300°C, Soldering time : 3sec. No strength on contact.		No deformation of case of excessive looseness of the terminals.		X -
Solderability 	Soldered at solder temperature, 240°C for insertion duration, 3sec.		Solder shall cover a minimum of 95 % of the surface being immersed.		X -
<b>Remarks</b>					
Note 1: Include the temperature rising by current.					
Note 2: No condensing.					
Note 3: Apply to the condition of long term storage for unused products before mounted on PCB. After mounted on PCB, operation temperature and humidity range is applied for interim storage during transportation.					
	Count	Description of revisions	Designed	Checked	Date
	5	DIS-H-00004896	HT. SATO	SZ. ONO	20190527
Unless otherwise specified, refer to IEC60512.			Approved	TS. SAKATA	20080401
			Checked	HK. UMEHARA	20080307
			Designed	TS. KUMAZAWA	20080307
			Drawn	YK. NAKATSU	20080229
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			Drawing no.		ELC-081815-50-01
	Specification sheet		Part no.	DF13-2P-1.25DS (50)	
	Hirose electric co., ltd.		Code no.	CL536-0151-7-50	 1/1